

Claims:

1. A semiconductor memory element, comprising:

a source region,

a drain region,

5 a channel region made of a semiconductor,

the source region and the drain region being connected by the channel region,

a gate electrode made of a metal or a

10 semiconductor for controlling the electric potential of the channel region, and

a plurality of charge storage regions in the vicinity of the channel region,

the electric potential to be applied to the gate electrode upon writing of data and the electric potential to be applied to the gate electrode upon 15 erasing of data having the same polarity.

2. A semiconductor memory element, comprising:

10 a channel region made of a semiconductor, the channel region including a first channel region which is a part of the channel region, and a second channel region which is a part of the channel region, and 20 different from the first channel region,

a plurality of charge storage regions in the vicinity of the channel region,

25 a first gate electrode made of a metal or a semiconductor for controlling the electric potential of the first channel region, and

a second gate electrode made of a metal or a

semiconductor for controlling the electric potential of the second channel region,

the electric potential to be applied to the first gate electrode upon writing of data and the electric potential to be applied to the first gate electrode upon erasing of data having the same polarity.

5 3. A semiconductor memory element, comprising:

10 a channel region made of a semiconductor, the channel region including a first channel region which is a part of the channel region, and a second channel region which is a part of the channel region, and different from the first channel region,

15 a plurality of charge storage regions in the vicinity of the channel region,

20 a first gate electrode made of a metal or a semiconductor for controlling the electric potential of the first channel region, and

25 a second gate electrode made of a metal or a semiconductor for controlling the electric potential of the second channel region,

the electric potential to be applied to the first gate electrode upon writing of data and the electric potential to be applied to the second gate electrode upon erasing of data having the same polarity.

4. A semiconductor memory element, comprising:

a source region,

a drain region,

a channel region made of a semiconductor, the

channel region including a first channel region which is a part of the channel region, and a second channel region which is a part of the channel region, and different from the first channel region,

5 the source region and the drain region being connected by the channel region,

a plurality of charge storage regions in the vicinity of the channel region,

10 a first gate electrode made of a metal or a semiconductor for controlling the electric potential of the first channel region, and

a second gate electrode made of a metal or a semiconductor for controlling the electric potential of the second channel region,

15 the electric potential to be applied to the first gate electrode upon writing of data and the electric potential to be applied to the first gate electrode upon erasing of data having the same polarity.

5. A semiconductor memory element, comprising:

20 a source region,

a drain region,

a channel region made of a semiconductor, the channel region including a first channel region which is a part of the channel region, and a second channel region which is a part of the channel region, and different from the first channel region,

the source region and the drain region being connected by the channel region,

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a plurality of charge storage regions in the vicinity of the channel region,

5 a first gate electrode made of a metal or a semiconductor for controlling the electric potential of the first channel region, and

10 a second gate electrode made of a metal or a semiconductor for controlling the electric potential of the second channel region,

15 the electric potential to be applied to the first gate electrode upon writing of data and the electric potential to be applied to the second gate electrode upon erasing of data having the same polarity.

20 6. A semiconductor memory device, comprising:

25 a memory cell array comprising a plurality of semiconductor memory elements, each comprising:

a source region,

a drain region,

30 a channel region made of a semiconductor, the channel region including a first channel region which is a part of the channel region, and a second channel region which is a part of the channel region, and different from the first channel region,

35 the source region and the drain region being connected by the channel region,

40 25 a plurality of charge storage regions in the vicinity of the channel region,

45 a first gate electrode made of a metal or a semiconductor for controlling the electric potential of

the first channel region, and

a second gate electrode made of a metal or a semiconductor for controlling the electric potential of the second channel region,

5 the plurality of the semiconductor memory elements being arranged in an array,

a data line,

a first word line, and

a second word line,

10 the memory cell array being driven by the data line, the first word line, and the second word line,

the drain regions of the plurality of the semiconductor memory elements being connected to the same data line,

15 the second gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different second word lines, and

20 the first gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different first word lines.

7. A semiconductor memory device, comprising:

25 a memory cell array comprising a plurality of the semiconductor memory elements according to claim 1,

the plurality of the semiconductor memory elements being arranged in an array,

a data line, and

a word line,

the memory cell array being driven by the data line and the word line,

5 the drain regions of the plurality of the semiconductor memory elements being connected to the same data line, and

the gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different word lines.

10 8. A semiconductor memory device, comprising:

a plurality of the semiconductor memory elements according to any of claims 1 to 3,

15 the plurality of the semiconductor memory elements being arranged,

a connection being established such that the channel currents of a first semiconductor memory element and a second semiconductor memory element flow in series.

20 9. A semiconductor memory device, comprising:

a memory cell array comprising a plurality of the semiconductor memory elements according to any of claim 4 or 5, the plurality of the semiconductor memory elements being arranged in an array,

25 a data line, and

a first word line,

the memory cell array being driven by the data line and the first word line,

the drain regions of the plurality of the semiconductor memory elements being connected to the same data line,

5 the second gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to one another, and

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10 the first gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different first word lines.

15 10. A semiconductor memory device, comprising:

15 a memory cell array comprising a plurality of the semiconductor memory elements according to any of claim 4 or 5, the plurality of the semiconductor memory elements being arranged in an array,

20 a data line, and

a first word line,

20 the memory cell array being driven by the data line and the first word line,

25 the drain regions of the plurality of the semiconductor memory elements being connected to the same data line,

25 the second gate electrodes of the plurality of the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different second word lines, and

the first gate electrodes of the plurality of

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the semiconductor memory elements of which the drain regions are connected to the same data line being connected to mutually different first word lines.